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ents or copy thereof.

To the Honorable Commissioner of Patents and Trademarks

1. Name of conveying party (ie. Jae Kun Lee)  
 Additional name(s) of conveying party?  
 Yes  No

NO FEB 11 PM 3:52  
 Jae Kun Lee  
 OPB/FINANCE

2. Name and address of receiving party(ies)

Name: Bokwang Co., Ltd.  
 Address: Glass Tower Building, 30F, 946-1 Daichidong, Kangnam-ku, Seoul 135-280, Korea

3. Nature of conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other \_\_\_\_\_

City: \_ State: \_ Zip: \_  
 Additional name(s) and address(es) attached?  
 Yes  No

Execution Date: December 22, 1999

4. Application number(s) or patent number(s)

If this document is being filed together with a new application, the execution date of the application is \_\_\_\_\_

A. Patent Application No.(s)  
 Serial No. 09/446,779 filed December 27, 1999

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Ronald B. Hildreth

BAKER BOTTS L.L.P.

Address: 30 Rockefeller Plaza - 44 Fl.

City: New York State: NY Zip: 10112

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 40.00

Enclosed  
 Authorized to be charged to deposit account

8. Deposit account number:  
02-4377  
 (Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature

*To the best of my knowledge and belief, the foregoing instrument is true and correct and any attached copy is a true copy of the original document.*

Ronald B. Hildreth

Name of Person Signing

Signature

January 24, 2000

Date

Total number of pages including cover sheet, attachments and document: 3

03/07/2000 VBROWN 00000020 024377 09466779

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PATENT  
 REEL: 010586 FRAME: 0781

A S S I G N M E N T

WHEREAS, I, JAE KUN LEE, a citizen of Korea, whose post office address is 130 Gongdan-dong, Gumi-Shi, Kyungsangbuk-do, 730-030, Republic of Korea has made an invention entitled "APPARATUS FOR EMBOLIC TREATMENT USING HIGH FREQUENCY INDUCTION HEATING" as set forth and described in application for Letters Patent of the United States Serial No.09/446,779 filed Dec. 27, 1999; and

WHEREAS, BOKWANG CO., LTD., a corporation organized and existing under the laws of Seoul, Korea, and having an office for the transaction of business at Glass Tower Bldg., 30F, 946-1 Daichi-dong, Kangnam-ku, Seoul 135-280, Republic of Korea, is desirous of acquiring the entire right, title and interest in and to said invention and any improvements thereon, and in and to the said application for Letters Patent therefor, and any Letters Patent which may be obtained therefor;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, BE IT KNOWN, that I, the said JAE KUN LEE, for and in consideration of the sum of One Dollar (\$1.00), lawful money of the United States, to me in hand paid by said BOKWANG CO., LTD., and other valuable considerations unto me moving from said BOKWANG CO., LTD., at or before the ensembling and delivery of these presents, the receipt of which is hereby acknowledged, have sold, assigned, transferred and conveyed and by these presents do sell, assign, transfer and convey, unto said BOKWANG CO., LTD., its successors and assigns, the entire right, title and interest in and to the said invention entitled "APPARATUS FOR EMBOLIC TREATMENT USING HIGH FREQUENCY INDUCTION HEATING" as set forth and described in application for Letters Patent of the United States Serial No.09/446,779 filed Dec. 27, 1999, and any and all improvements thereon, and in and to said application and any division, continuation or continuation-in-part thereof, and in and to any Letters Patent of the United States which may be issued on any of said applications, and any reissues thereof, and in and to any and all applications for Letters Patent filed in foreign countries for said invention or improvements, including all priority rights under the Paris Convention, and any and all Letters Patent which may be granted in foreign countries therefor, TO HAVE AND TO HOLD THE SAME to the full end of the term or terms for which any and all said Letters Patent may be granted;

AND I, the said JAE KUN LEE, do hereby authorize and request the Commissioner of Patents and Trademarks to issue the said Letters Patent of the United States to said BOKWANG CO., LTD., as the assignee of the entire right, title and interest in and to the same, for the sole use and behoof of said BOKWANG CO., LTD., its successors and assigns;

AND I, the said JAE KUN LEE, for the considerations aforesaid, do hereby covenant and agree to and with said BOKWANG CO, LTD., its successors and assigns, that I have the full power to make this assignment, and that the rights assigned are not encumbered by any grant, license or right heretofore given, and that I, my executors or administrators, shall and will do all lawful acts and things and make, execute and deliver without further compensation, any and all other instruments in writing, further applications, papers, affidavits, powers of attorney, assignments, and other documents which, in the opinion of counsel for said BOKWANG CO., LTD., its successors and assigns, may be required or necessary to more effectively secure to and vest in said BOKWANG CO., LTD., its successors and assigns, the entire right, title and interest in and to said invention and improvements, applications, Letters Patent, rights, benefits, privileges and advantages hereby sold, assigned, transferred and conveyed, and that I will sign any applications for reissue which may be desired by the owner of the patent or patents which may be issued for the said invention or improvements.

Subscribed and executed at \_\_\_\_\_  
(Place)

on 12/22/1999.  
(Date)

J. K. Lee  
JAE KUN LEE

Witness: \_\_\_\_\_  
(Type Name)

Witness: \_\_\_\_\_  
(Type Name)